

LP5951 Evaluation Board

National Semiconductor
Application Note 1486
Klaus Scheitinger
September 2006



Introduction

This evaluation board is designed to enable independent evaluation of the LP5951 electrical performance. Each board is pre-assembled and tested in the factory.

The evaluation kits are available in two options: LP5951MF-1.8EV and LP5951MF-2.5EV. For other voltage and package options, the device can be ordered from LP5951 product folder on National's website. The board offers two different assembly options: SC70-5 package (MG) on top side (TOP) or SOT23-5 package on bottom side (BOT) of the board. Only one side will be assembled at a time.

General Description

The LP5951 converts high input voltages to lower output voltages while consuming low quiescent current. The LP5951 is capable of operating with an input voltage range from 1.8V to 5.5V for fixed output voltage options from 1.3V to 3.3V. The LP5951 can supply a maximum output current of 150mA and is particularly suitable for portable, battery-powered systems. It also features internal protection against short-circuit currents and over-temperature conditions.

The input voltage, applied between V_{IN} and GND should be at least 0.35V above the output voltage to operate the device

out of dropout with a minimum of 1.8V and no higher than 5.5V. Input connections should be kept reasonably short (<30cm) to minimise input inductance and ensure optimum transient performance.

ON/OFF control of the LP5951 is provided on the evaluation board by a logic signal applied to the V_{EN} pin. To simplify the enabling of the device, a three pin jumper is provided on the board. The middle pin is directly connected to the V_{EN} pin of the device. A logic signal with a minimum of 0.9V to enable the device or with a maximum of 0.4V to disable the device can be directly connected to this jumper pin in the middle. Alternatively the middle pin can be shorted to the pin next to it to the left or to the right marked OFF or ON.

A load of 150mA maximum may be connected from the V_{OUT} pin to GND.

At the bottom of each side of the board the package (SC70-5 or SOT23-5) and the output voltage option (1.3V, 1.5V, 1.8V, 2.0V, 2.5V, 2.8V, 3.0V or 3.3V) is printed.

The V_{OUT_S} pin represents a sense path to the output voltage pin and can be used for more precise voltage measurements.

The schematic and board layout are shown below:

Schematic Diagram

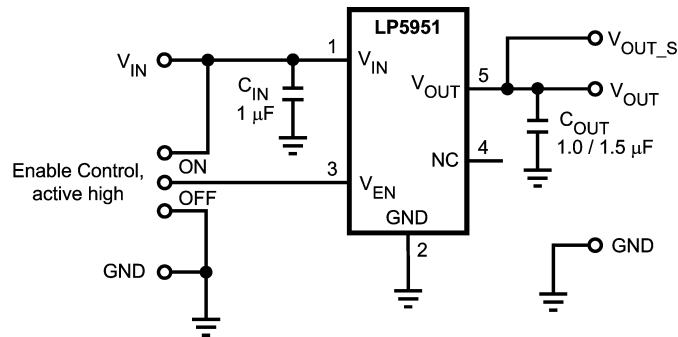
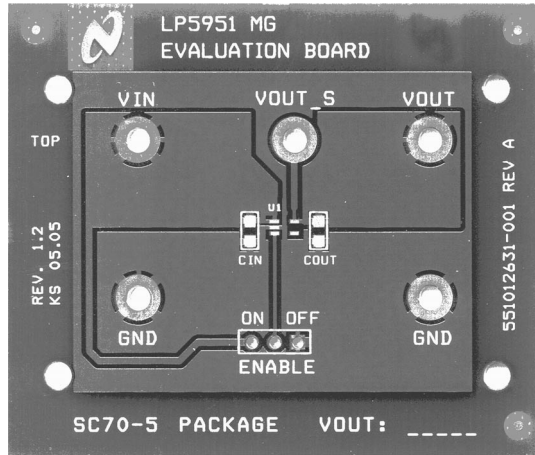


FIGURE 1: Evaluation Board Schematic

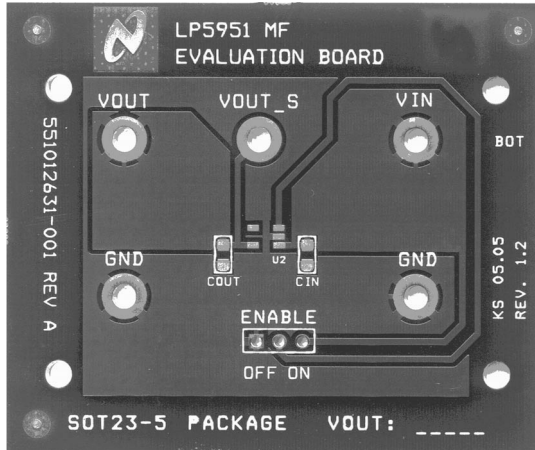
20195101

Evaluation Board Component and Pin Layout



20195111

FIGURE 2: TOP Side, SC70-5 Package (MG)
Board Size: 60mm x 50mm



20195112

FIGURE 3: BOTTOM Side, SOT23-5 Package (MF)

Connection Diagrams

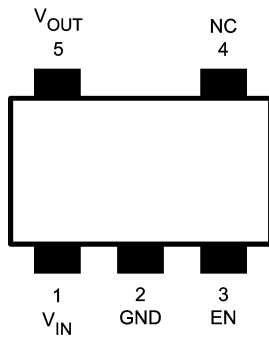


FIGURE 4: SOT23-5 (MF), Top View

20195104

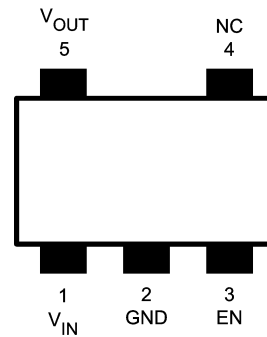


FIGURE 5: SC70-5 (MG), Top View

20195105

Pin Descriptions

Pin #	Name	Description
1	V _{IN}	Input voltage. Input range: 1.8V to 5.5V
2	GND	Ground
3	EN	Enable pin logic input: Low = shutdown, High = normal operation. This pin should not be left floating. Short to V _{IN} using attached jumper for normal operation.
4	NC	No internal connection
5	V _{OUT}	Regulated output voltage

Bill of Materials

Item	Description	Amount	Footprint	Mfg., Part Number
C _{IN}	Ceramic capacitor, 1μF, X5R	1	0603	TDK, C1608X5R1A105K
C _{OUT}	Ceramic capacitor, 1μF, X5R or Ceramic capacitor, 1.5μF, X5R	1	0603	TDK, C1608X5R1A105K (for 1.3V to 2.5V options) or TDK, C1608X5R1C155K (for 2.8V to 3.3V options)
U ₁ or U ₂	LP5951 LDO Regulator	1	SC70-5 or SOT23-5	National Semiconductor, LP5951MG-x.x or National Semiconductor, LP5951MF-x.x
V _{IN} , V _{OUT_S} , V _{OUT} , GND	Test pins	5		Cambion, 160-1026-02-05

Application Hints

POWER DISSIPATION AND DEVICE OPERATION

The permissible power dissipation for any package is a measure of the capability of the device to pass heat from the power source, the junctions of the IC, to the ultimate heat sink, the ambient environment. Thus the power dissipation is dependent on the ambient temperature and the thermal resistance across the various interfaces between the die and ambient air.

The allowable power dissipation for the device in a given package can be calculated using the following equation:

$$PD = (T_{J(MAX)} - T_A) / \theta_{JA}$$

With a $\theta_{JA} = 220^\circ\text{C/W}$, the device in the SOT23-5 package returns a value of 454mW with a maximum junction temperature of 125°C at T_A of 25°C . For the SC70-5 package with a $\theta_{JA} = 415^\circ\text{C/W}$, the device returns a value of 241mW.

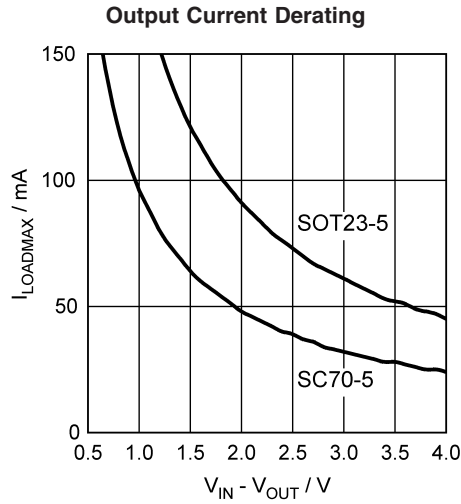
The actual power dissipation across the device can be estimated by the following equation:

$$P_D \approx (V_{IN} - V_{OUT}) * I_{OUT}$$

This establishes the relationship between the power dissipation allowed due to thermal consideration, the voltage drop across the device, and the continuous current capability of the device. These two equations should be used to determine the optimum operating conditions for the device in the application.

Application Hints (Continued)

Based on these considerations the following 'Output Current Derating' can be calculated:



20195106
**FIGURE 6: Maximum Load Current vs (V_{IN} - V_{OUT}),
 T_A = 85°C, V_{OUT} = 1.5V**

EXTERNAL CAPACITORS

A ceramic capacitor of 1.0μF is recommended and assembled at the input (C_{IN}).

At the output (C_{OUT}) the following ceramic capacitors are suitable:

- V_{OUT} < 2.8V: 1.0μF
- V_{OUT} ≥ 2.8V: 1.5μF.

For further details on recommended capacitors and capacitor characteristics please see bill of materials above and the datasheet.

National does not assume any responsibility for use of any circuitry described, no circuit patent licenses are implied and National reserves the right at any time without notice to change said circuitry and specifications.

For the most current product information visit us at www.national.com.

LIFE SUPPORT POLICY

NATIONAL'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT AND GENERAL COUNSEL OF NATIONAL SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

BANNED SUBSTANCE COMPLIANCE

National Semiconductor follows the provisions of the Product Stewardship Guide for Customers (CSP-9-111C2) and Banned Substances and Materials of Interest Specification (CSP-9-111S2) for regulatory environmental compliance. Details may be found at: www.national.com/quality/green.

Lead free products are RoHS compliant.



National Semiconductor
Americas Customer
Support Center
 Email: new.feedback@nsc.com
 Tel: 1-800-272-9959

National Semiconductor
Europe Customer Support Center
 Fax: +49 (0) 180-530 85 86
 Email: europa.support@nsc.com
 Deutsch Tel: +49 (0) 69 9508 6208
 English Tel: +44 (0) 870 24 0 2171
 Français Tel: +33 (0) 1 41 91 8790

National Semiconductor
Asia Pacific Customer
Support Center
 Email: ap.support@nsc.com

National Semiconductor
Japan Customer Support Center
 Fax: 81-3-5639-7507
 Email: jpn.feedback@nsc.com
 Tel: 81-3-5639-7560

www.national.com